Nova AncoFlex™

Fully Automated
Copper Plating Analyzer

Proven Performance in PCB / IC-Substrate Manufacturing Environment with Automatic Verification and Calibration

Supports a broad variety of copper electroplating chemistries

Benefits

Fully Automated Metrology

- Excellent lifetime monitoring of bath composition and performance
- Accuracy and Repeatability – Reported and controlled
- High reliability combined with minimal service needs
- Upgradable to other Copper plating chemistries, as needed

Low Cost of Ownership

- Low Cost of Ownership – long parts lifetime with low PM cost of
- Small footprint, minimal facilities requirements

Data Transparency

- All analysis data and information can be extracted by the user for data analysis

Low Cost of Ownership
Longer parts lifetime,
Small footprint

Transparent Data Access
User access to all data
Analog and digital fab links

Fully Automated
Accurate, repeatable results
Upgradeable

Nova AncoFlex™ Features

Cu Plating Analyzer – Designed for the PCB industry

- Supports a broad variety of Copper Electroplating (Currently galvanic deposition) Chemistries
- Fully automated analyses of bath components: metal and additives
- Simple operation and maintenance

Minimizes downtime

- Automatic verification (plausibility check) of results
- Auto Calibration with plausibility function
- Analog and Digital communication to process tools and the Fab
  - RS-232, TCP/IP, Analog 4-20 mA

Low Cost of Ownership with a Proven Record

Typical performance in Cu plating processes

Component	Technique	Accuracy (*) [%]	RSD (*) [%]	Analysis time
Copper	Spectrometry	3	2	Total Analysis time < 90 min*)
Acid	Titration	3	2	
Chloride	Titration	3	2	
Accelerator	CVS	7.5	7	
Suppressor	CVS	7.5	7	
Leveler	CVS / Spectroscopy	7.5	7	

* Chemistry dependent

NOVA PROCESS INSIGHT

Nova Ancolyzer®

The Leading Fully Automated Process Control for Advanced Packaging

Flexible, Scalable Tailored to the Application

Leading process control for Advanced Packaging

- Electroplating: Cu, Ni, SnAg, Sn, In and Au
- Electroless (e-Less) plating: e-less Ni and Pd, Immersion Au, e-less Au and Cu
- Pre-treatment for e-less plating: wetter, pre-dip, post-dip, Cu-etch, Ni-activator, Al-etch and Zincation

Flexible, open system architecture

- Full access to collected data
- Enhances characterization, troubleshooting, and process improvement

... characterizes both physical and chemical properties - analyzes **Inorganic** and **Organic** components, **Breakdowns** and also **Bath Performance/Behavior**

Nova Leadership
Know-how in chemical metrology and process control

- Proven leadership in the packaging domain
- Broad range of techniques and methodologies
- Seamless chemical fully automated replenishment, bleed & feed and bath make up

Delivering exceptional value to the end customer

- Controlling chemical costs and waste reduction due to lower chemical consumption
- Longer consumable parts lifetime and refurbishment options for lowest CoO
- Designed for easy field upgradeability

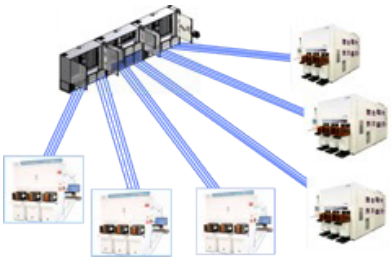
Low Cost of Ownership
Longer parts lifetime,
Efficient footprint

Transparent Data Access
User access to all data
Analog and digital fab links

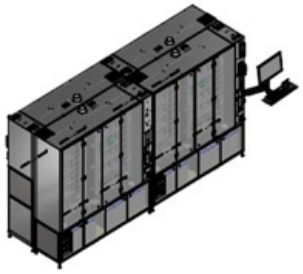
WLP Best Performance
Accurate, repeatable results
Upgradeable

A Family of Automated Process Control Workstations

Analysis and dosing systems



Larger complex systems for multiple plating and dosing steps

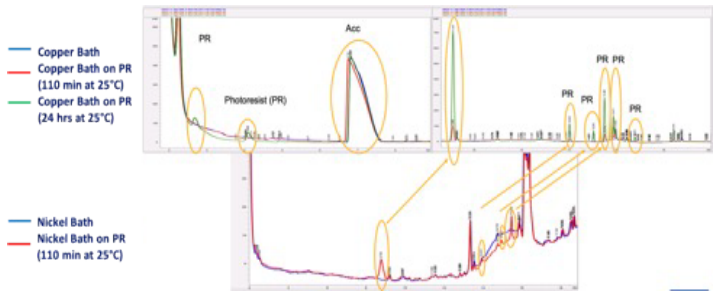


- Up to 5 frames can be combined into one system
- Front access only allows back-to-back positioning

Nova Ancolyzer® Features

- Supports all known chemistries including:
  - Plating: Copper, Tin-Silver, Pure Tin, Nickel and Gold
  - Electroless deposition for Panels and IC-Substrates: Surface preparation (desmear), Electroless Ni, Pd, immersion Au
- The preferred metrology by all major suppliers of Advanced Packaging chemicals
- Analysis of all bath components required for optimal plating
- Intelligent replenishment based on multiple process inputs
  - Replenishment from plating process containers
  - Replenishment from facility bulk
- Seamless DMR integration (CoO lowering solution for low alpha tin/tin silver and Cu plating
- Precise and validated mixing of Standards, Makeup Solutions, dilutions
- Standards: SEMI S2/S8, F47, CE
- Full fab communications support
- Utilizes chemical vendors' containers, Nowpak ready, Barcode assisted
- SW GUI includes data analysis, logs and reports, graphic SPC and preventive maintenance

Bath Lifecycle Contaminants analysis



Nova AncoScene™

Back-End-Of-Line Interconnects Metrology for Damascene Plating

Benefits

- Automated online analysis of inorganics, organic additives and byproducts
- Smallest footprint and fab space
- Simple, convenient front access
- Cu & Acid - non reagent analysis (NRA)
- Connection to all typical plating tools
- Automatic Standard mixing with self-check provisions
- Barcode verification system for bottle changes
- Supports NowPak containers
- Long parts lifetime and refurbishment options for lowest CoO

Low Cost of Ownership

Longer p arts lifetime,
Small footprint

Transparent Data Access

User access to all data
Analog and digital fab links

Fully Automated

Accurate, repeatable results
Proven, successful delivery record

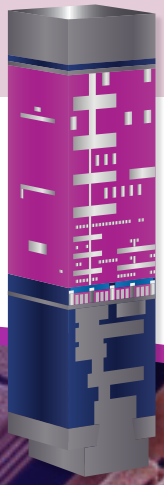
Nova AncoScene™ Features

- Supports all copper chemistries
- Optional Bath Health/Performance Indicator
- Precise and validated mixing of Standards
- Safety Standards: SEMI S2/S8, F47, CE
- Communication protocols: TCP-IP, RS-232, SECS/GEM
- Containers: Nowpak ready, Barcode assisted container replacement system
- SW GUI includes: data analysis, logs and reports, graphic SPC and preventive maintenance
- Slip-Streams: up to 4 tanks
- FM-4910 compliant material
- MTBF > 2160 hours; MTTR ~ 2 Hours
- Footprint: 810mm W x 610mm D

Analysis Performance – Cu Damascene

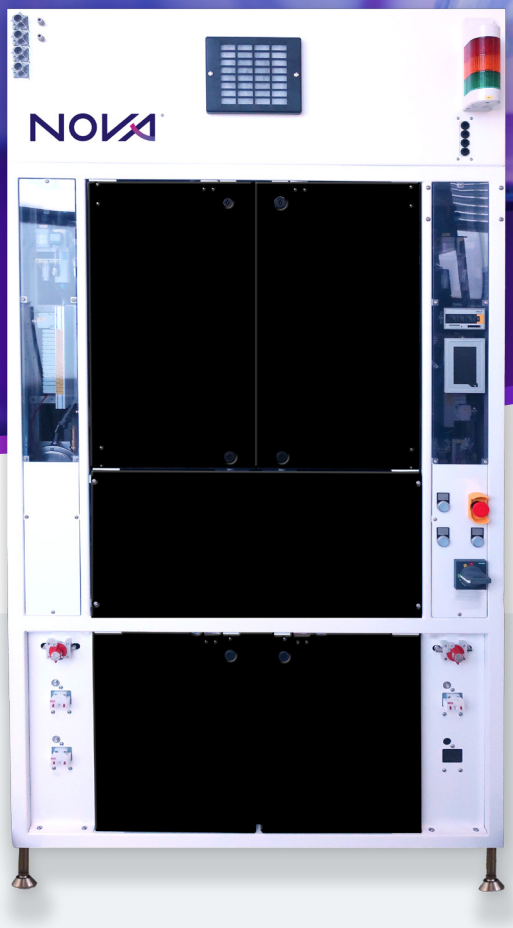
Component	Technique	Accuracy [%]	RSD [%]	Analysis time
Copper	Spectrometry	2	1	Total time 30min*
Sulfuric Acid	Non-Reagent	2	1	
Chloride	Titration	3	2	
Accelerator	CVS	3	2	
Leveler		3	2	
Suppressor		3	2	

* Bath chemistry dependent



Nova DMR®

Inline continuous Direct Metal Replenishment (DMR) for cost-effective metal plating



BENEFITS

- Available for Cu VMS and Sn MSA Bath
- The only clean room ready Metal-oxide replenisher in the market
- Process optimization:
  - Minimizes need for Bleed & Feed by eliminating the constant increase in bath volume
  - Improves up time by reducing the need for anode change PM
  - Eliminates issues with plating uniformity at high anode utilization rates
- Economical and shelf stable Metal source
- 50% to 80% direct cost savings in Advanced packaging applications: RDL, Cu Pillars, TSV
- Patented technology

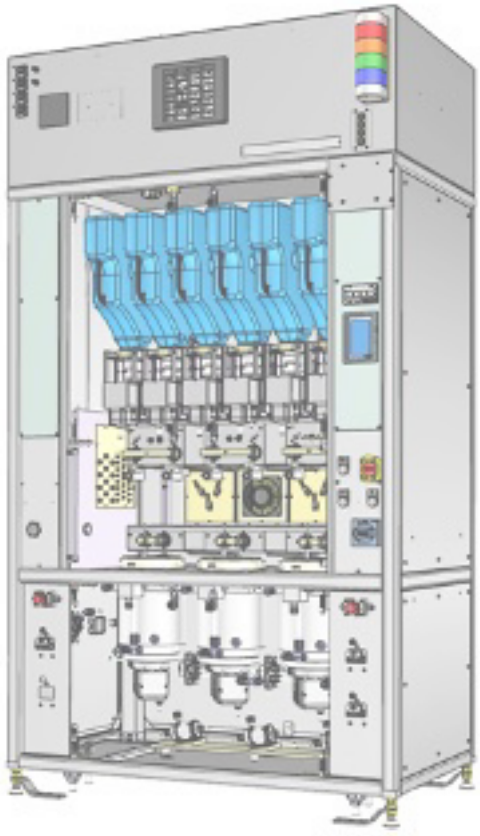
Low Cost of Ownership
Longer parts lifetime, Small footprint

Patented Technology
The only Powder Doser for OSATs and Fabs

Fully Automated
Container loader for docking and undocking

Nova DMR® Features

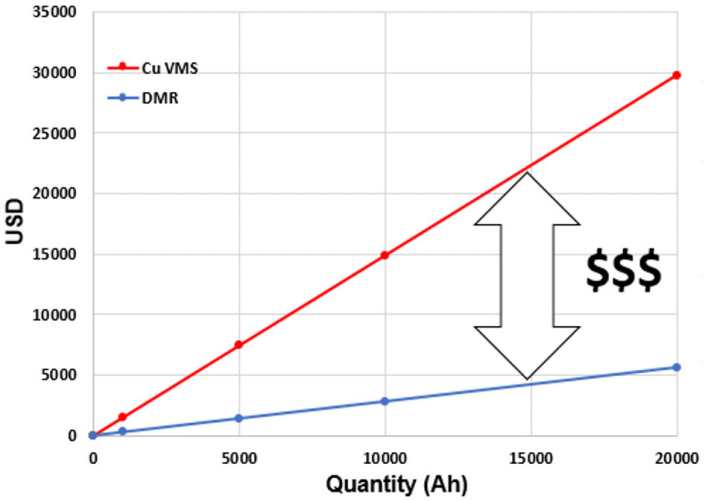
Optimizes High Volume Metal Plating Processes



- Supports up to 3 DMR Stations
  - Multiple DMR Stations can be connected to one plating tank to increase dosing throughput
- Supports multiple platers
- High-capacity containers:
  - 10 kg CuO (replenish up to 165g/hr per Station) – For Cu applications
  - 5 kg SnO (225 g/hr per Station) – For SnAg and Pure Sn applications
- Secure material management via RFID:
  All containers are scannable on the Tool with RFID encoded:
  - CoA information
  - Material, Lot & Product No.
  - Lot history and expiration date are tracked
- Safety Standards: S2/S8, F47, CE
- Multiple material suppliers qualified

50% to 80% direct cost savings in Advanced Packaging

Cu Replenishment by DMR vs. VMS - CoO Calculation



- H_2SO_4 level remains constant on a set level
- Bath volume stays steady without significant increase, thus preventing frequent bleed
- Stable Cu source
- Very long shelf-Life in a solid state

NOVA